SDLS147 - SEPTEMBER 1972 - REVISED MARCH 1988

- Three-State Version of SN54/74LS153, SN54/74S153
- Schottky-Diode-Clamped Transistors
- Permits Multiplexing from N Lines to 1 Line
- Performs Parallel-to Serial Conversion
- Fully Compatible with Most TTL Circuits
- Low Power Dissipation

'LS253 . . . 35 mW Typical 'S253 . . . 225 mW Typical

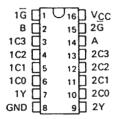
#### description

Each of these Schottky-clamped data selectors/multiplexers contains inverters and drivers to supply fully complementary, on-chip, binary decoding data selection to the AND-OR gates. Separate output control inputs are provided for each of the two four-line sections.

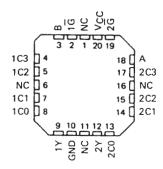
The three-state outputs can interface with and drive data lines of bus-organized systems. With all but one of the common outputs disabled (at a high-impedance state) the low-impedance of the single enabled output will drive the bus line to a high or low logic level.

SN54LS253, SN54S253 . . . J OR W PACKAGE SN74LS253, SN74S253 . . . D OR N PACKAGE

(TOP VIEW)



# SN54LS253, SN54S253...FK PACKAGE (TOP VIEW)



NC-No internal connection

#### **FUNCTION TABLE**

1	ECT UTS		DATA	INPUTS	OUTPUT CONTROL	ОUТРUТ	
В	Α	CO	C1	C2	C3	Ğ	Υ
X	X	X	X	X	X	Н	Z
Ł	L	L	X	X	Х	L	L
L	L	Н	X	×	X	L	н
L	Н	X	L	X	Х	L	L
L	Н	X	Н	X	X	L	н
Н	L	X	X	L	X	L	L
н	L	X	X	Н	X	L	Н
Н	Н	X	X	X	L	L	L
Н	Н	Х	×	X	Н	L	Н

Address inputs A and B are common to both sections.

H = high fevel, L = low level, X = irrelevant, Z = high impedance (off)

#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

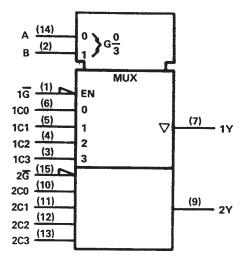
Supply voltage, VCC (see Note 1)			 7 V
Input voltage: 'LS253			 7 V
′S253			 5.5 V
Off-state output voltage			
Operating free-air temperature range	: SN54LS253, SN54S253	, <b></b>	 - 55°C to 125°C
	SN74LS253, SN74S253		
Storage temperature range			 $-65^{\circ}$ C to $150^{\circ}$ C

NOTE 1: Voltage values are with respect to network ground terminal.

TEXAS INSTRUMENTS

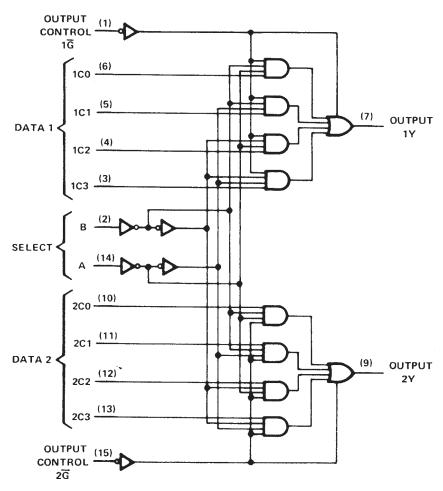
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#### logic symbol†



<sup>&</sup>lt;sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

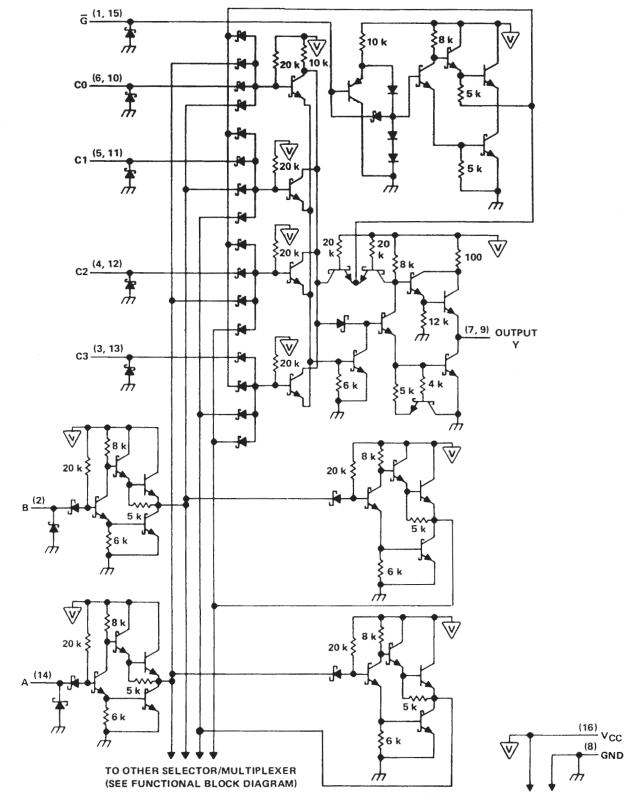
### logic diagram (positive logic)



Pin numbers shown are for D, J, N, and W packages.



schematic (each selector/multiplexer, and the common select section)



Pin numbers shown are for D, J, N, and W packages.



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#### recommended operating conditions

		S	SN54LS253			SN74LS253			
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	V	
VIH	High-level input voltage	2			2			V	
VIL	Low-level input voltage			0.7			0.8	V	
Іон	High-level output current			- 1			2.6	mA	
IOL	Low-level output current			4			8	mA	
TA	Operating free-air temperature	- 55		125	0		70	°C	

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS <sup>†</sup>						S	N74LS2	53	LINIT
FANAMETEN		1521 CONDITI	ONS		MIN	TYP \$	MAX	MIN	TYP‡	MAX	UNIT
VIK	VCC = MIN,	$I_1 = -18 \text{ mA}$					- 1.5			1.5	V
VOH	V <sub>CC</sub> = MIN,	V <sub>IH</sub> = 2 V,	VIL = MAX,	1 <sub>OH</sub> = MAX	2.4	3.4		2.4	3.1		V
VOL	V <sub>CC</sub> = MIN,	V <sub>IH</sub> = 2 V,	1/ - 14AV	IOL = 4 mA		0.25	0.4		0.25	0.4	V
VOL	ACC - MIIA'	VIH - 2 V,	VIL = MAX	IOL = 8 mA					0.25	0.5	\ \
loz	VCC = MAX,	V <sub>IH</sub> = 2 V		V <sub>O</sub> = 2.7 V			20			20	
102	VCC - WAX,	VIH - Z V		V <sub>O</sub> = 0.4 V			- 20			20	μΑ
11	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 7 V					0.1			0.1	mA
liH.	V <sub>CC</sub> = MAX,	V <sub>I</sub> = 2.7 V					20			20	μΑ
1	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 0.4 V		Ğ			- 0.2			- 0.2	
115	VCC - MAA,	V   - 0.4 V		All other			- 0.4			- 0.4	, mA
Ios§	V <sub>CC</sub> = MAX				- 30		- 130	- 30		- 130	mA
loo	V <sub>CC</sub> = MAX,	See Note 2		Condition A		7	12		7	12	
¹cc	VCC - WAA,	See Note 2		Condition B		8.5	14		8.5	14 mA	

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value spcified under recommended operating conditions.

NOTE 2: I<sub>CC</sub> is measured with the outputs open under the following conditions:

## switching characteristics, $V_{CC}$ = 5 V, $T_A$ = 25°C

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
<sup>t</sup> PLH	Data	Y			17	25	
tPHL	Data	'			13	20	ns
<sup>t</sup> PLH	Select		$C_L = 15 pF$ , $R_L = 2 k\Omega$ ,		30	45	
tPHL.	Select	'	See Note 3		21	32	ns
<sup>t</sup> PZH	Output	_			15	28	
<sup>t</sup> PZL	Control	'			15	23	ns
<sup>t</sup> PHZ	Output		$C_L = 5 \text{ pF}, \qquad R_L = 2 \text{ k}\Omega,$		27	41	
<sup>t</sup> PLZ	Control		See Note 3		18	27	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



<sup>‡</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ} \text{C}$ .

<sup>§</sup> Not more than one output should be shorted at a time, and duration for the short-circuit should exceed one second.

A. All inputs grounded.

B. Output control at 4.5 V, all inputs grounded.

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#### recommended operating conditions

		S	SN54S253			SN74S253		
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.8			0.8	V
ЮН	High-level output current			-2			- 6.5	mA
IOL	Low-level output current			20			20	mA
TA	Operating free-air temperature	- 55		125	0		70	°C

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER			MIN	түр‡	MAX	UNIT			
VIK	VCC = MIN,	I <sub>I</sub> = - 18 mA			-1.2	V			
Voн	VCC = MIN,	V <sub>1H</sub> = 2 V,	V <sub>1L</sub> = 0.8 V,	IOH = MAX	Series 54S	2,5	3.4		V
*OH	VCC - WITH,	VIH - 2 V,	VIL - 0.8 V,	IOH = MAX	Series 74S	2.7	3.4		1 V
VOL	VCC = MIN,	VIH = 2 V,	VIL = 0.8 V,	IOL = 20 mA				0.5	V
loz	Vcc = MAX,	VIH = 2 V			V <sub>O</sub> = 2.4 V			50	
.02	VCC - WAX,	VIH - 2 V			V <sub>O</sub> = 0.5 V			- 50	μA
l <sub>1</sub>	V <sub>CC</sub> = MAX,	V1 = 5.5 V						1	mA
ΙΗ	V <sub>CC</sub> = MAX,	V <sub>I</sub> = 2.7 V						50	μΑ
111	V	V 0.5.V.			G = 0.8 V			- 2	
-11.	VCC = MAX,	$V_1 = 0.5 V$			G = 2 V			- 0.25	mA
los§	V <sub>CC</sub> = MAX				1	- 40		- 100	mA
lcc	CC V <sub>CC</sub> = MAX, See Note 2	See Note 2	Condition				45	70	
	TOG = WAX,	See Note 2	Condition B		65	85	mA		

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

Not more than one output should be shorted at a time and duration of short-circuit should not exceed one second.

NOTE 2: I<sub>CC</sub> is measured with the outputs open under the following conditions:

- A. All inputs grounded.
- B. Output control at 4.5 V, all inputs grounded.

#### switching characteristics, $V_{CC} = 5 \text{ V}$ , $T_A = 25^{\circ} \text{C}$

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CON	MIN TYP	MAX	UNIT	
<sup>t</sup> PLH	Data	~			6	9	
<sup>t</sup> PHL	Data	'			6	9	ns
<sup>t</sup> PLH	Select		$R_L = 280 \Omega$	C <sub>L</sub> = 15 pF	11.5	18	
<sup>t</sup> PHL	Jociect	'	See Note 3	or lob!	12	18	ns
<sup>t</sup> PZH	Output		***************************************		11	16.5	
<sup>t</sup> PZL	Control	,			12	18	ns
<sup>t</sup> PHZ	Output	~	$R_L = 280 \Omega$ ,	C <sub>L</sub> = 5 pF	6.5	9.5	
<sup>t</sup> PLZ	Control	'	See Note 3		10	15	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



<sup>‡</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ} \text{C}$ .



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#### **PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
76017012A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	76017012A SNJ54LS 253FK	Samples
7601701EA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	7601701EA SNJ54LS253J	Samples
7601701EA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	7601701EA SNJ54LS253J	Samples
JM38510/30908BEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30908BEA	Samples
JM38510/30908BEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30908BEA	Samples
JM38510/30908BFA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30908BFA	Samples
JM38510/30908BFA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30908BFA	Samples
M38510/30908BEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30908BEA	Samples
M38510/30908BEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30908BEA	Samples
M38510/30908BFA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30908BFA	Samples
M38510/30908BFA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30908BFA	Samples
SN54LS253J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS253J	Samples
SN54LS253J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS253J	Samples
SN74LS253DR	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS253	Samples
SN74LS253DR	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS253	Samples
SN74LS253N	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS253N	Samples
SN74LS253N	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS253N	Samples



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Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SNJ54LS253FK	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	76017012A SNJ54LS 253FK	Samples
SNJ54LS253FK	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	76017012A SNJ54LS 253FK	Samples
SNJ54LS253J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	7601701EA SNJ54LS253J	Samples
SNJ54LS253J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	7601701EA SNJ54LS253J	Samples

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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## PACKAGE OPTION ADDENDUM

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#### OTHER QUALIFIED VERSIONS OF SN54LS253, SN74LS253:

Catalog: SN74LS253

Military: SN54LS253

NOTE: Qualified Version Definitions:

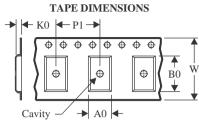
- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

## **PACKAGE MATERIALS INFORMATION**

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#### TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	U	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS253DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1

## **PACKAGE MATERIALS INFORMATION**

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#### \*All dimensions are nominal

	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
ı	SN74LS253DR	SOIC	D	16	2500	340.5	336.1	32.0

## **PACKAGE MATERIALS INFORMATION**

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#### **TUBE**



\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
76017012A	FK	LCCC	20	1	506.98	12.06	2030	NA
JM38510/30908BFA	W	CFP	16	1	506.98	26.16	6220	NA
M38510/30908BFA	W	CFP	16	1	506.98	26.16	6220	NA
SN74LS253N	N	PDIP	16	25	506	13.97	11230	4.32
SN74LS253N	N	PDIP	16	25	506	13.97	11230	4.32
SNJ54LS253FK	FK	LCCC	20	1	506.98	12.06	2030	NA

## D (R-PDS0-G16)

#### PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



## D (R-PDSO-G16)

## PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



## W (R-GDFP-F16)

## CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP2-F16



8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



## 14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

## N (R-PDIP-T\*\*)

## PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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